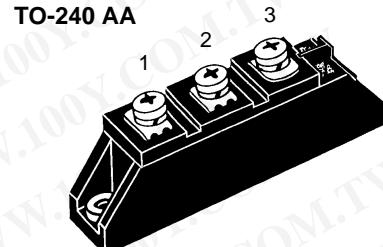
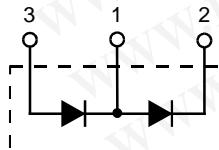


Diode Modules

勝特力材料 886-3-5753170
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I_{FRMS} = 2x 60 A
I_{FAVM} = 2x 36 A
V_{RRM} = 800-1800 V

V _{RSM} V	V _{RRM} V	Type
900	800	MDD 26-08N1 B
1300	1200	MDD 26-12N1 B
1500	1400	MDD 26-14N1 B
1700	1600	MDD 26-16N1 B
1900	1800	MDD 26-18N1 B



Symbol	Test Conditions	Maximum Ratings		
I _{FRMS}	T _{VJ} = T _{VJM}	60	A	
I _{FAVM}	T _C = 100°C; 180° sine	36	A	
I _{FSM}	T _{VJ} = 45°C; V _R = 0	650	A	
	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	760	A	
	T _{VJ} = T _{VJM} V _R = 0	580	A	
	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	630	A	
∫I ² dt	T _{VJ} = 45°C V _R = 0	2100	A ² s	
	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	2400	A ² s	
	T _{VJ} = T _{VJM} V _R = 0	1700	A ² s	
	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	1900	A ² s	
T _{VJ}		-40...+150	°C	
T _{VJM}		150	°C	
T _{stg}		-40...+125	°C	
V _{ISOL}	50/60 Hz, RMS	t = 1 min	3000	V~
	I _{ISOL} ≤ 1 mA	t = 1 s	3600	V~
M _d	Mounting torque (M5)	2.5-4/22-35	Nm/lb.in.	
	Terminal connection torque (M5)	2.5-4/22-35	Nm/lb.in.	
Weight	Typical including screws	90	g	

Symbol	Test Conditions	Characteristic Values		
I _R	T _{VJ} = T _{VJM} ; V _R = V _{RRM}	10	mA	
V _F	I _F = 80 A; T _{VJ} = 25°C	1.38	V	
V _{To}	For power-loss calculations only	0.8	V	
r _T	T _{VJ} = T _{VJM}	6.1	mΩ	
Q _S	T _{VJ} = 125°C; I _F = 25 A, -di/dt = 0.6 A/μs	50	μC	
I _{RM}		6	A	
R _{thJC}	per diode; DC current	1.0	K/W	
	per module	0.5	K/W	
R _{thJK}	per diode; DC current	1.2	K/W	
	per module	0.6	K/W	
d _s	Creepage distance on surface	12.7	mm	
d _A	Strike distance through air	9.6	mm	
a	Maximum allowable acceleration	50	m/s ²	

Data according to IEC 60747 and refer to a single diode unless otherwise stated.
 IXYS reserves the right to change limits, test conditions and dimensions

Features

- International standard package JEDEC TO-240 AA
- Direct copper bonded Al₂O₃ -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873

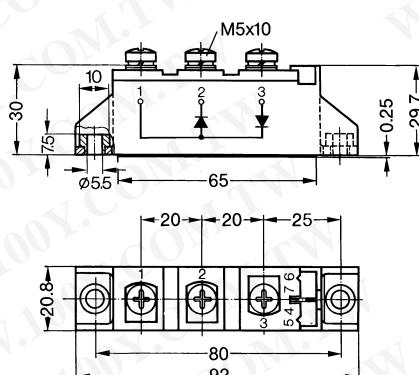
Applications

- Supplies for DC power equipment
- DC supply for PWM inverter
- Field supply for DC motors
- Battery DC power supplies

Advantages

- Space and weight savings
- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

Dimensions in mm (1 mm = 0.0394")



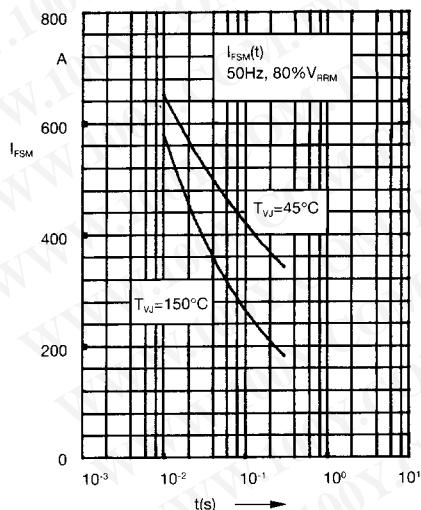


Fig. 1 Surge overload current
 I_{FSM} : Crest value, t : duration

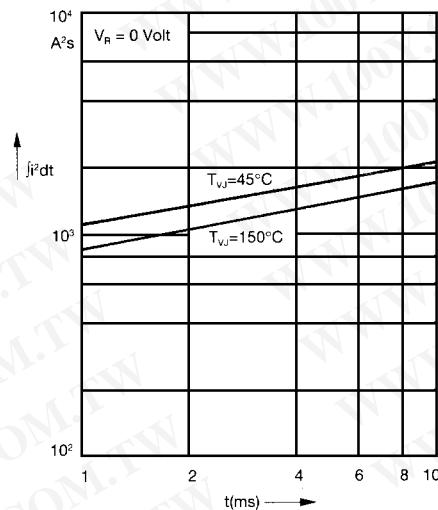


Fig. 2 j^2dt versus time (1-10 ms)

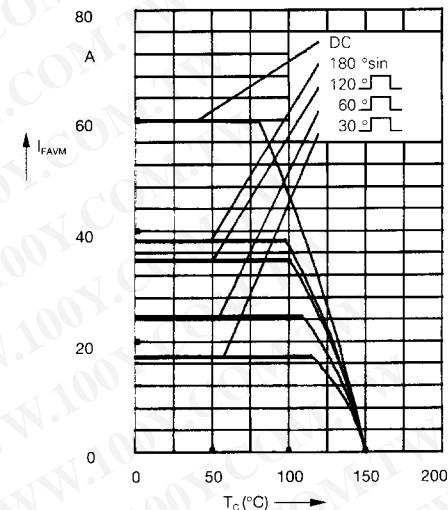


Fig. 2a Maximum forward current
at case temperature

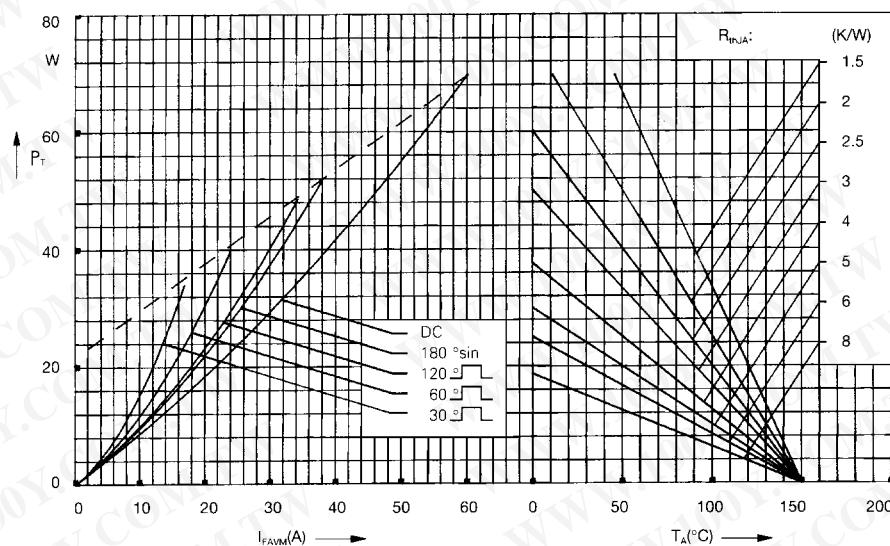


Fig. 3 Power dissipation versus
forward current and ambient
temperature (per diode)

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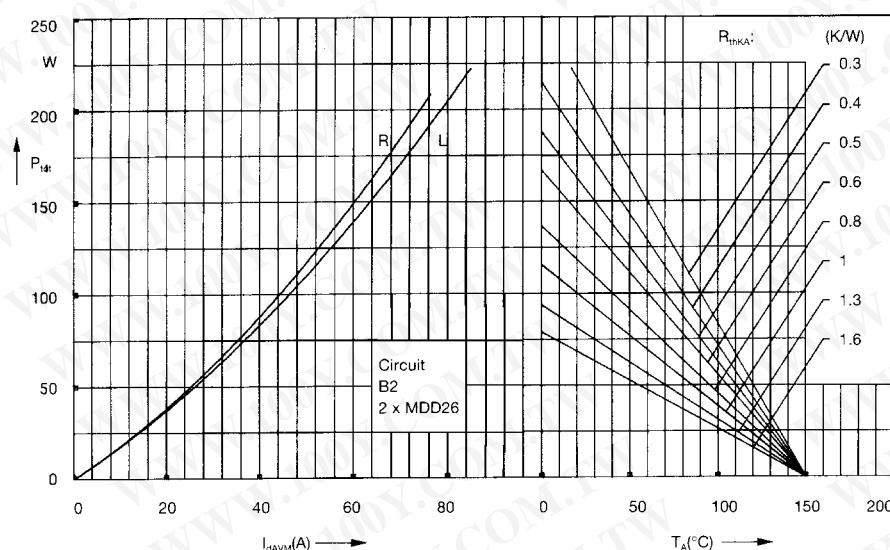


Fig. 4 Single phase rectifier bridge:
Power dissipation versus direct
output current and ambient
temperature
R = resistive load
L = inductive load

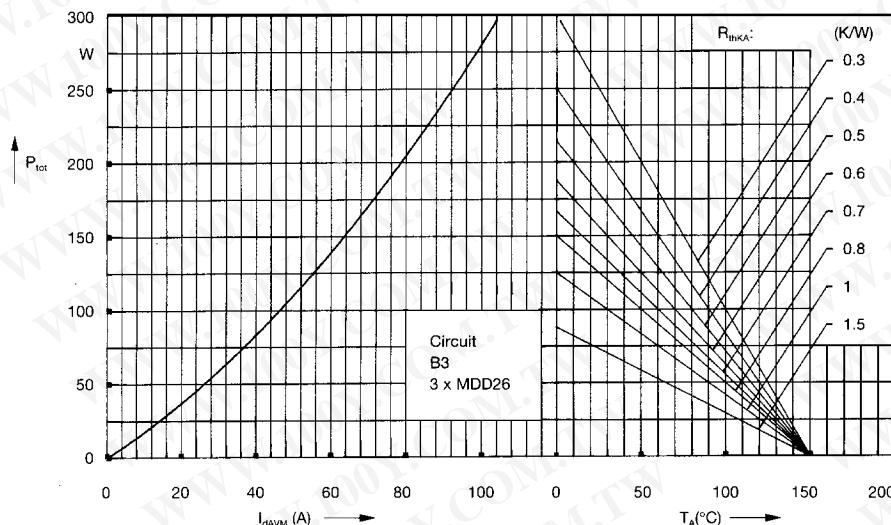


Fig. 5 Three phase rectifier bridge:
Power dissipation versus direct
output current and ambient
temperature

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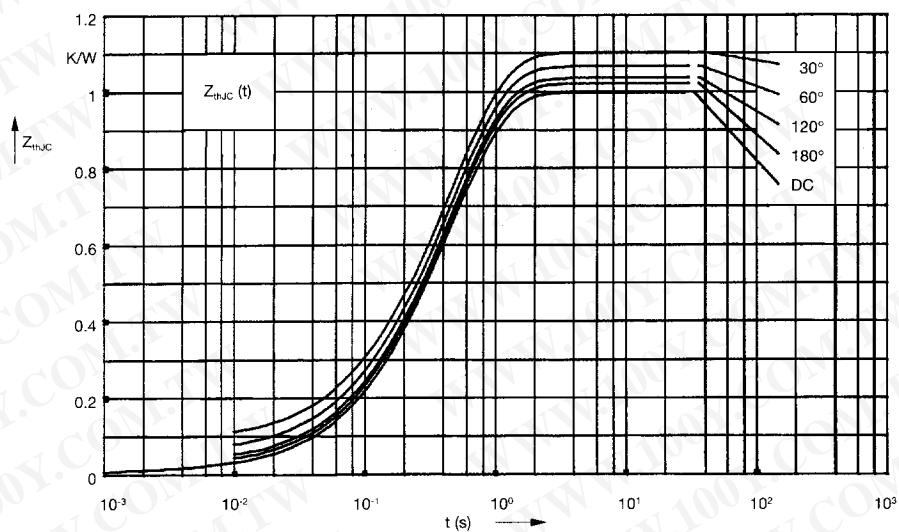


Fig. 6 Transient thermal impedance
junction to case (per diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	1.00
180°	1.02
120°	1.04
60°	1.07
30°	1.10

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.01	0.0012
2	0.03	0.095
3	0.96	0.455

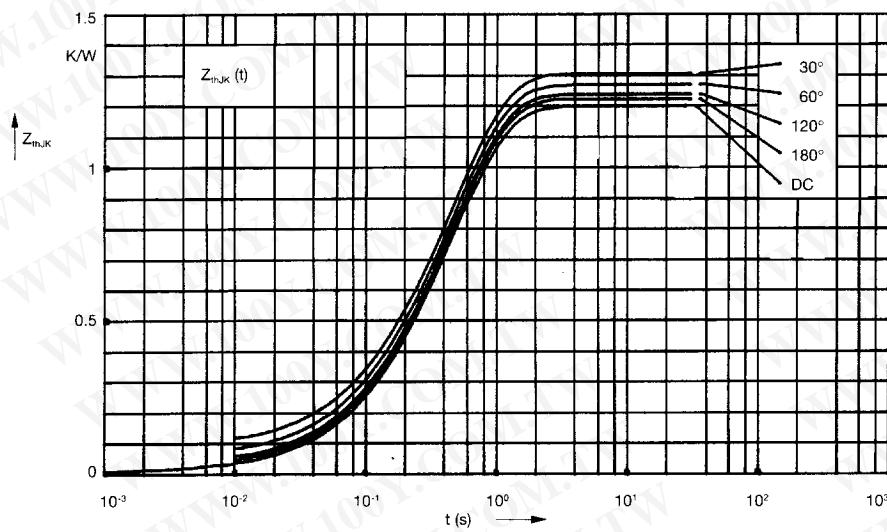


Fig. 7 Transient thermal impedance
junction to heatsink (per diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	1.20
180°	1.22
120°	1.24
60°	1.27
30°	1.30

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.01	0.0012
2	0.03	0.095
3	0.96	0.455
4	0.2	0.495